# DuPont 9475R

**AgPd Pt Conductor Composition** 

## **EUROPEAN TECHNICAL DATASHEET**

All values reported here are results of experiments in our laboratories intended to illustrate product performance potential with a given experimental design. They are not intended to represent the product's specifications, details of which are available upon demand

## **Product Description**

DuPont 9475R Ag/Pd/Pt conductor is designed to be used for large aluminium wire bonding. It is intended to be applied to ceramic substrates by screen printing and fired in a conveyor furnace in an air (oxidising) atmosphere. It has been developed to offer excellent performance on alumina for component attachment, resistor termination and large aluminium wire bonding.

#### **Product Benefits :**

- Bondable with thick 250 aluminium wire
- Optimised for 30 minute 850°C firing profile
- Phthalate, Cadmium, Nickel oxide free\*

\* Phthalate, Cadmium and Nickel oxide 'free' as used herein means that cadmium, phthalate and nickel oxide are not intentional ingredients in and are not intentionally added to the referenced product. Trace amounts however may be present

## **Processing Summary**

• Screen Type

200-250 mesh stainless steel screen with a 12-14  $\mu m$  emulsion build up.

Drying

Allow prints to level for over 10 minutes at room temperature, then dry for  $\geq$  10 -15 minutes at 150°C

 Firing 850°C peak held for 10 minutes on 30 minute cycle in an air atmosphere

## Compatibility

Whilst DuPont has tested this composition with the materials specified above and the recommended processing conditions,

it is impossible or impractical to cover every combination of materials, customer processing conditions and circuit layouts. It is therefore essential that customers thoroughly evaluate the material in their specific situations in order to completely satisfy themselves with the overall quality and suitability of the composition for its intended application (s).

## **Storage and Shelf Life**

Containers may be stored in a clean, stable environment at room temperature (between  $5^{\circ}C - 30^{\circ}C$ ) with their lids tightly sealed. Storage in high temperature (<30°C) or in freezers (temperature <0°C) is NOT recommended as this could cause irreversible changes in the material. The shelf life of compositions in factory-sealed (unopened) containers between ( $5^{\circ}C - 30^{\circ}C$ ) is 6 months from date of shipment.

## **Substrates**

Substrates of different compositions and from various manufacturers may result in variations in performance properties

## **TABLE 1. TYPICAL PHYSICAL PROPERTIES**

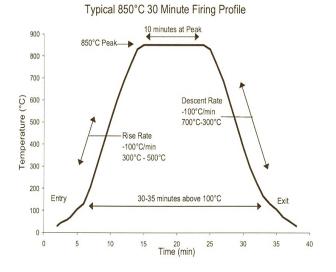
Viscosity (Pa.s.)	83–113	
(Haake cone and plate rheometer, 30 seconds		
shear at 33s-1, temperature 23+/-0.5°	C)	
Coverage [cm <sup>2</sup> /g]	72-77	
Based on fired thickness of $14 \mu m$		
Shrinkage [%]		
Dried to fired	40-45	
Thinner	9180R	
Shelf Life (months)	6	

## Thinner

9475R composition is optimized for screen printing and thinning is not normally required. Use the DuPont recommended thinner for slight adjustments to viscosity or to replace evaporation losses. The use of too much thinner or the use of a non recommended thinner may affect the rheological behaviour of the material and its printing characteristics. Please refer to table 1.Typical Physical Properties'



## **CHART 1. FIRING PROFILE**



#### **Printing**

The composition should be thoroughly mixed before use. This is best achieved by slow, gentle hand stirring with a clean burr-free spatula (flexible plastic or stainless steel) for about 1-2 minutes. Care must be taken to avoid air entrapment. Printing should be performed in a well ventilated area. Additional information on requirements for printing areas is contained in DuPont Technical Guide EUT 7.3 'Processing-Screen Printing Rooms' available on request.

Note: optimum printing characteristics are generally achieved in the room temperature range of 20°C-23°C. It is therefore important that the material, in its container, is at the temperature prior to commencement of printing. Class 10,000 printing area is recommended for building complex hybrids and multilayer circuits, otherwise severe yield losses could occur. Refer to 'Processing Summary'.

## Drying

Allow prints to level at room temperature, then dry in a well ventilated oven or conveyor dryer. Refer to 'Processing Summary'.

## **Firing**

Fire in well ventilated belt, conveyor furnace or static furnace. Air flows and extraction rates should be optimized to ensure that oxidizing conditions exist within the muffle and that no exhaust gases enter the room.

Full information on requirements for firing is contained in DuPont Technical Guide EUT 7.4 'Process Guide-Firing'. Refer to 'Processing Summary'.

## General

Performance will depend to a large degree on care exercised in screen printing. Scrupulous care should be taken to keep the composition, printing screens and other tools free of metal contamination. Dust, lint and other particulate matter may also contribute to poor yields.

TABLE 2. TYPICAL FIRED PROPERTIES <sup>1</sup>	
Fired Thickness (μm)	10—14
TCR (ppm/°C)	350-450
<b>Resistivity on alumina [m<math>\Omega</math>/<math>\Box</math>] (@ 12<math>\mu</math>m fired thickness)</b>	<u>≤</u> 40
Solder Acceptance <sup>2</sup>	
62Sn/36Pb/2Ag@220°C	≥90% coverage
Solder Leach Resistance	
62Sn/36Pb/2Ag @230°C	6 cycles
Adhesion [N] <sup>3</sup>	
Initial (1xfiring)]	≥20
Aged 48hrs@ 150°C	≥18
250μm Al wire bonding on alumina <sup>4</sup>	
Initial	<u>&gt;</u> 350g
1000 hrs @ 10°C	<u>&gt;</u> 250g
Test Procedure	
1 Typical properties are based on laboratory data using recommended proc	<b>.</b>
expressly noted elsewhere the following processing conditions have been us Printing: 200 mesh stainless steel screen, 12-14µm emulsion thickness	sed:
Firing: 3x 30 minute cycles to a peak temperature of 850°C for 10 minutes	
Tested on 96% alumina substrates	
2 Using Alpha 611 flux. Solder coverage measured after a 5s dip in solder. A leaching cycle is represented	
by a 10s dip in solder and tested on 500μm lines. See soldering test procedure for details (H- 1.12) 3 90° wire peel test on 2mmx 2mm pads soldered with 62Sn/36Pb/2Ag solder at 220°C and using a mildly	
activated Alpha 611. See wire peel adhesion test procedure for details (E-3.12)	
4 Orthodyne Model 20, double V groove, tool force 350g, 250μm Al wire (99 ensile strength 370-450g (Ε-3.16S)	9.99%), elongation 10-15%, t

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